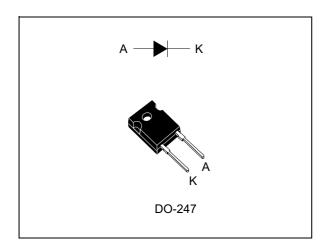


STTH30ACS06W

Turbo 2 ultrafast high voltage rectifier

Datasheet - production data



Features

- Ultrafast switching
- Low reverse current
- · Low thermal resistance
- Reduces switching and conduction losses

Description

The STTH30ACS06W, which is ST Turbo 2 600 V technology, is suited as boost diode especially in air conditioning equipment for continuous mode interleaved power factor correction.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	30 A
V _{RRM}	600 V
T _j (max)	175 °C
V _F (typ)	1.45 V
t _{rr} (max)	30 ns

Characteristics STTH30ACS06W

1 Characteristics

Table 2. Absolute ratings (limiting values at T_i = 25 °C, unless otherwise specified)

	<u> </u>	•	<u> </u>	
Symbol	Parameter	Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		600	V
I _{F(RMS)}	RMS forward current 50 A			
I _{F(AV)}	Average forward current	30	Α	
I _{FSM}	Surge non repetitive forward current	190	Α	
T _{stg}	Storage temperature range	-65 to +175	°C	
T _j	Maximum operating junction temperature	+175	°C	

Table 3. Thermal parameters

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	1.2	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Test cond	ditions	Min.	Тур.	Max.	Unit	
I _R ⁽¹⁾	Payaraa laakaga aurrant	T _j = 25 °C	V V	-		5	μA	
'R`	Reverse leakage current	T _j = 150 °C	$V_R = V_{RRM}$	-	30	300	μΑ	
V _E ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _E = 30 A	-		2.4	V	
, k.,	V _F ⁽²⁾ Forward voltage drop		$T_j = 150 ^{\circ}\text{C}$	1F = 30 A	-	1.45	1.9	\ \ \

- 1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$
- 2. Pulse test: t_p = 380 μ s, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 1.42 \times I_{F(AV)} + 0.016 \times I_{F}^{2}_{(RMS)}$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions			Тур.	Max.	Unit
			$I_F = 0.5 \text{ A}, I_{rr} = 0.25 \text{ A}, I_R = 1 \text{ A}$			30	ns
t _{rr}	Reverse recovery time	T _j = 25 °C	$I_F = 1 \text{ A}, V_R = 30 \text{ V},$ $dI_F/dt = -50 \text{ A}/\mu\text{s}$		40	55	ns
I _{RM}	Reverse recovery current	T _j = 125 °C	$I_F = 30 \text{ A,d}I_F/dt = 200 \text{ A/}\mu\text{s}, \ V_R = 400 \text{ V}$		7.8	10.5	Α
t _{fr}	Forward recovery time	T _i = 25 °C	$I_F = 30 \text{ A,dI}_F/\text{dt} = 200 \text{ A/}\mu\text{s},$			300	ns
V_{FP}	Forward recovery voltage	1, -25 0	V _{FR} = 2.8 V		3.5		V

STTH30ACS06W Characteristics

Figure 1. Average forward power dissipation versus average forward current $\mathsf{P}_{\mathsf{F}(\mathsf{AV})}(\mathsf{W})$ 80 70 60 50 40 30 20 10 0 10 15 25 30 35 40

Figure 2. Forward voltage drop versus forward current (typical values)

Figure 3. Forward voltage drop versus forward current (maximum values)

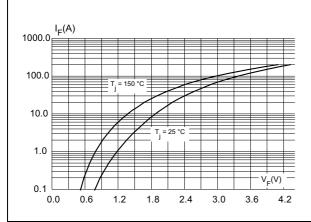


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

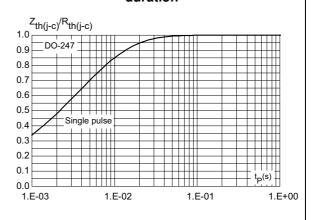


Figure 5. Peak reverse recovery current versus dl_F/dt (typical values)

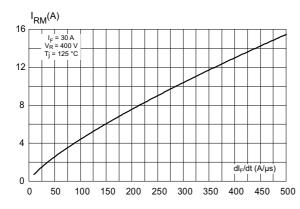
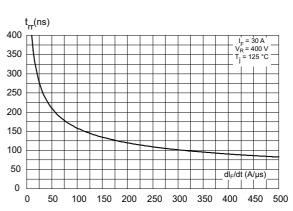


Figure 6. Reverse recovery time versus dl_F/dt (typical values)



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Figure 7. Reverse recovery charges versus dl_F/dt (typical values) $Q_{rr}(nC)$ 900 I_E = 30 V 800 700 600 500 400 300 200 100 dl_F/dt (A/µs)_ 0 0 100 150 200 250 300 350 400 450 500

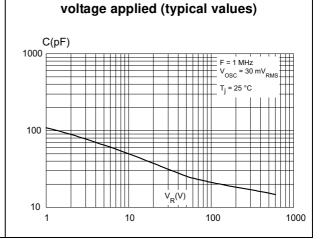
Figure 8. Softness factor versus dl_F/dt (typical values) S_{factor} 4.0 I_F = 30 V _F = 30 V -V_R = 400 V T_j = 125 °C 3.0 2.0 1.0 dl_F/dt (A/µs) 0.0 150 200 250 300 350 400 450 500

Figure 9. Relative variations of dynamic parameters versus junction temperature 1.4 I_F = 30 V V_R = 400 V erence: T_j = 1 1.2 1.0 0.8 0.6 0.4

75

Figure 10. Transient peak forward voltage versus dl_F/dt (typical values) $V_{FP}(V)$ I_F = 30 A T_j = 125 °C 6 2 dl_F/dt (A/μs) 100 150 200 250 300 350 400 450 500

Figure 11. Forward recovery time versus dl_E/dt | Figure 12. Junction capacitance versus reverse (typical values) $t_{fr}(ns)$ 200 I_F = 30 A V_{FR} = 1.9 V T_j = 125 °C 150 100 50 dl_F/dt (A/µs) 100 150 200 250 300 350 400 450 500



0.2

0.0 25

50

T_i(°C)

125

100

2 **Package information**

- Epoxy meets UL94, V0
- Cooling method by conduction (C)
- Recommended torque value: 0.8 N·m
- Maximum torque value: 1.0 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

DO-247 package information 2.1

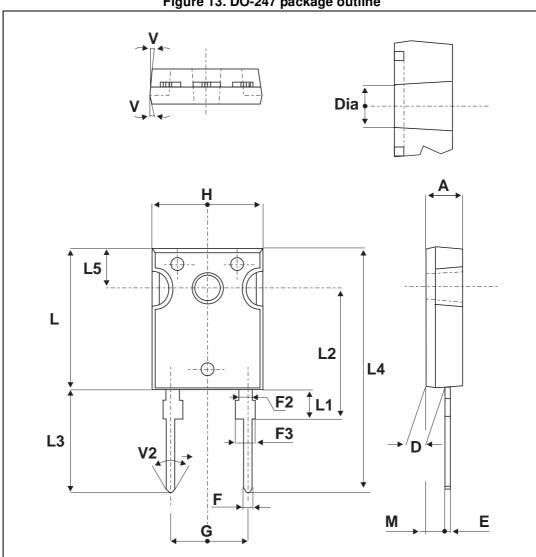


Figure 13. DO-247 package outline

Package information STTH30ACS06W

Table 6. DO-247 package mechanical data

			Dime	nsions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
Н	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
М	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH30ACS06W	STTH30ACS06W	DO-247	1.8 g	50	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
22-Sep-2015	1	First issue.

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